

AMENDMENT TO THE CLAIMS

1. (Currently amended) A semiconductor device, comprising:

a semiconductor wiring substrate including a plurality of wires;

a chip IP including a circuit having semiconductor device elements arranged therein, the chip IP being attached to and mounted on the semiconductor wiring substrate; ~~so that the circuit is electrically connected to the plurality of wires of the semiconductor wiring substrate; and~~

at least one test pad connected to at least one of the wires of the semiconductor wiring substrate ~~for testing an electrical connection between the circuit of the chip IP and the wires; and~~

a switching element provided at a position along at least one of the wires of the semiconductor wiring substrate and opposite to the chip IP with respect to the test pad, the switching element turning off transmission of a signal from the test pad while testing an electrical connection between the circuit of the chip IP and at least one of the wires.

2. (Withdrawn) The semiconductor device of claim 1, wherein the test pad is an external terminal pad of the semiconductor device.

3. (Original) The semiconductor device of claim 1, wherein the test pad is a portion of the at least one of the wires that is exposed on a surface of the semiconductor wiring substrate.

4. (Currently amended) The semiconductor device of claim 1, wherein:

the circuit of the chip IP includes a power supply line for supplying a power supply voltage and a node, and a protection diode, through which a forward current flows when a negative voltage ~~of the opposite polarity~~ is applied to the power supply line, between the power supply line and the node; and

said at least one test pad includes a first test pad connected to a wire that is connected to the power supply line and a second test pad connected to a wire that is connected to the node in the circuit.

5. (Currently amended) The semiconductor device of claim 1, wherein:

the circuit of the chip IP includes a ground line for supplying a ground voltage and a node, and a protection diode, through which a forward current flows when a positive voltage ~~of the opposite polarity~~ is applied to the ground line, between the ground line and the node; and

said at least one test pad includes a first test pad connected to a wire that is connected to the ground line and a second test pad connected to a wire that is connected to the node in the circuit.

6. (Withdrawn) The semiconductor device of claim 1, wherein: the circuit of the chip IP includes a ground line for supplying a ground voltage, a power supply line for supplying a power supply voltage, and a selector for receiving, and selectively outputting one of, a signal of the ground line or the power supply line and an output signal of an output section of the circuit; and the test pad includes a first test pad connected to a wire for

supplying a switching control signal for the selector and a second test pad connected to an output section of the selector.

7. (Canceled)

8. (Withdrawn) The semiconductor device of claim 1, further comprising: a test circuit provided in the chip IP for testing an electrical connection between the circuit of the chip IP and the wires; and a setting circuit for setting at least the test circuit in a test mode, wherein the test pad includes a first test pad for supplying a test mode signal to the test circuit and the setting circuit and a second test pad for receiving an output of the test circuit.

9. (Withdrawn) The semiconductor device of claim 8, wherein the test circuit has a pull-down type circuit structure or a pull-up type circuit structure.

10. (Withdrawn) The semiconductor device of claim 8, wherein the setting circuit is provided in the chip IP.

11. (Withdrawn) The semiconductor device of claim 8, wherein the setting circuit is provided in a chip different from the chip IP.

12. (Withdrawn) The semiconductor device of claim 8, wherein: the circuit of the chip IP includes a power supply line for supplying a power supply voltage and a ground line

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for supplying a ground voltage; and the semiconductor device further comprises: a third pad connected to a wire that is connected to the power supply line; and a fourth pad connected to a wire that is connected to the ground line.

13-20. (Canceled)